



SW Test Workshop
Semiconductor Wafer Test Workshop

***“SMART” Laser Drilling for
Advanced Vertical Probe Card
Manufacturing***



Alan Ferguson, Ph.D
Oxford Lasers

June 5-8, 2016

Overview

Introduction

Advanced Vertical Probe Cards

Historical Review

“SMART” Program

Results

Future R & D Targets

Summary

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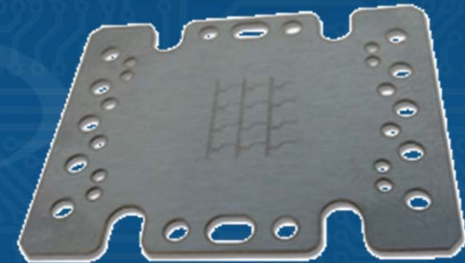
Introduction

- **Guide Plates**

- Are an essential component in Vertical probe cards.
- Consist of 1000's micro-holes through which probes are fitted, ensuring accurate location of each probe.
- Typical probe card uses several guide plates.

- **Guide Plate Features**

- Accurately locate probe pins.
- Pin size and pitch to match DUT.
- Appropriate current capacity, impedance, contact resistance etc.
- Appropriate guiding/sliding of pins, scrub, wear, cleaning etc.
- Mechanically stable substrate.
- Match CTe to DUT.



Advanced Vertical Probe Cards

- **Advanced Vertical Probe Card Types**

- Cobra
- Micro-pogo
- MEMs

- **Minimum Probe Pitch**

- Reducing from 120um to <50um.
- Driven by transition from solder bump to copper pillar.

- **Materials**

- Ceramics (SiN, Alumina, Macerite, Photoveel).
- Polymers: Polyimides, (Kapton, Vespel, Cirlex), PEEK.



Historical Review

2015



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Semiconductor Wafer Test Workshop
June 7 - 10, 2015 | San Diego, California

Drilling Methods and Materials for Advanced Vertical Probe Cards



Alan Ferguson, Ph.D
Oxford Lasers

2014



IEEE SW Test Workshop
Semiconductor Wafer Test Workshop
June 8 - 11, 2014 | San Diego, California

Challenges and Solutions in future designs of Vertical Probe Cards



Alan Ferguson
Oxford Lasers

2008

IEEE SW Test Workshop
Semiconductor Wafer Test Workshop




Dr. Alan Ferguson
Oxford Lasers

Comparison of Drilling Rates and Tolerances of Laser-Drilled holes in Silicon Nitride and Polyimide Vertical Probe Cards



June 8-11, 2008
San Diego, CA USA

2005



Laser Micromachining: A flexible tool in Vertical Probe Card Manufacturing

D.Karnakis, M.Knowles

Oxford Lasers Ltd., Moorbrook Park, Didcot OX11 7HP (UK)

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Historical Review

What we have shown and presented :

- Demonstrated the use of Lasers in Probe Card Drilling (2005)
- Demonstrated Practical and Economic Drill Speeds (2008)
- Demonstrated the Over Coming of Challenges in the Industry (2014)
- Demonstrated a variety of drilling methods and materials (2015)

Now to the next Level :

Project SMART

Smart is a UK Government fund to help companies, to engage in R&D projects in the strategically important areas of science, engineering and technology.

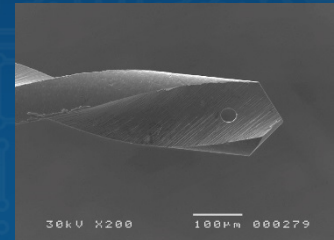
Started December 2015

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Innovate UK Smart – Non Round Holes

Why Square or Rectangular Holes ?

More and more requests for rectangular / square micro holes
Probes can achieve softer touchdowns
Probes are of lower cost

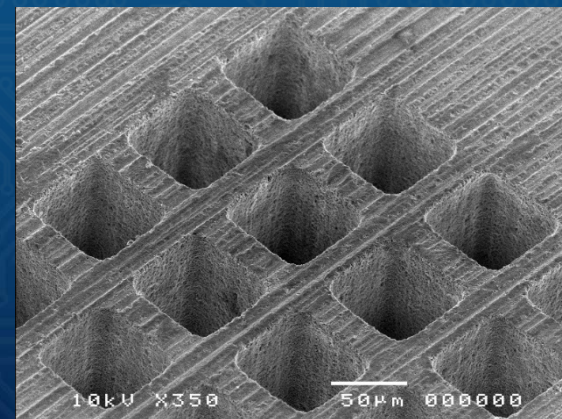


Why Laser Drilling ?

Can't make a square hole with a round mechanical drill bit.

What are the Issues ?

Rounded / Square corners
Hole Taper
Stability
Speed

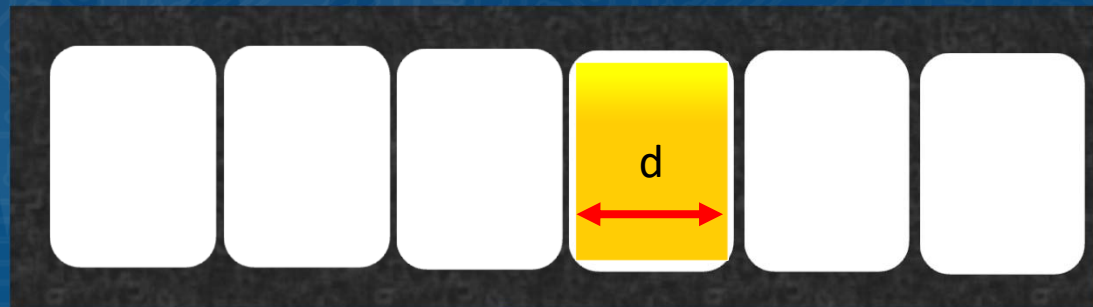


Goals of the Project

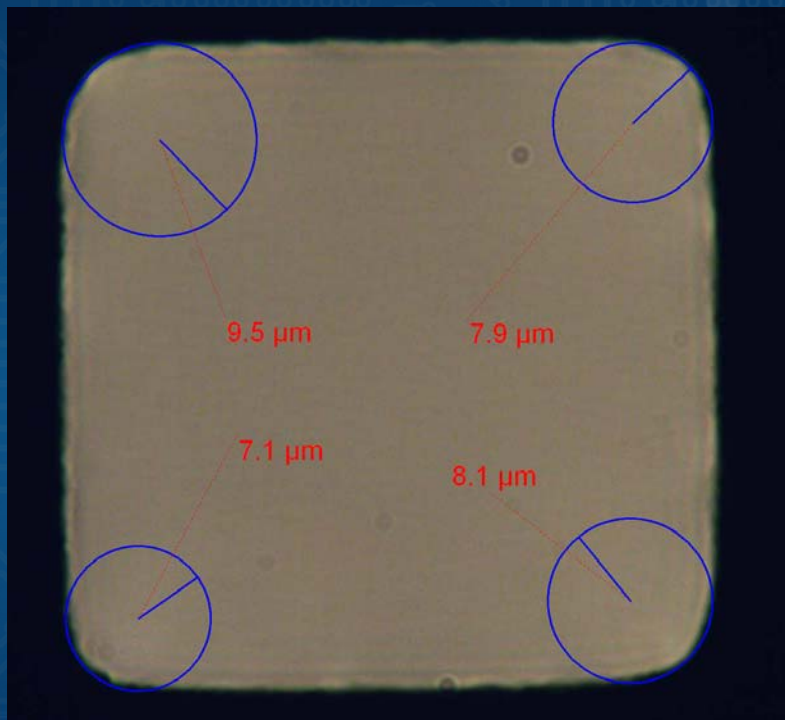
- a) Decrease the corner radius for square holes
- b) Maintain taper at under $2\mu\text{m}$ for all holes
- c) Improve the positional accuracy of microholes
- d) Improve the roundness of round holes
- e) Improve / Reduce hole size variation
- f) Increase the drill speed for all holes

Importance of Reduced Corner Radius

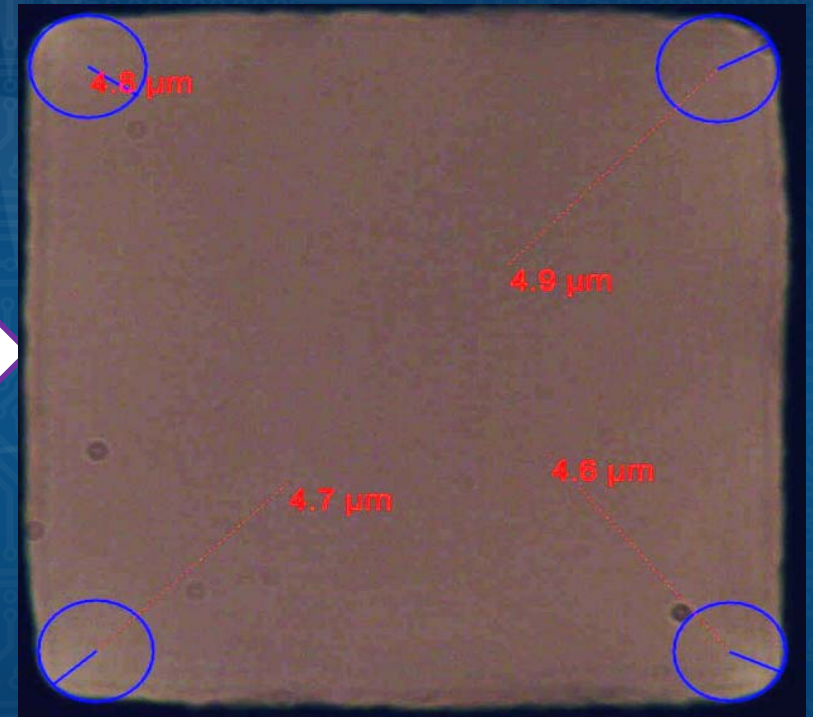
While the pin size “d” is the same, the larger corner radii **reduces** the **possible minimum pitch** of holes



Preliminary Results



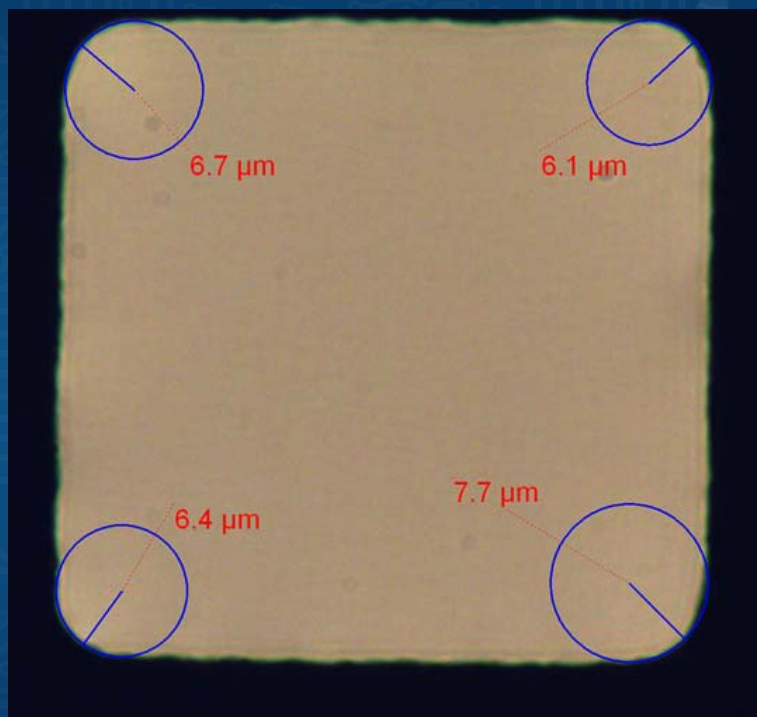
SMART



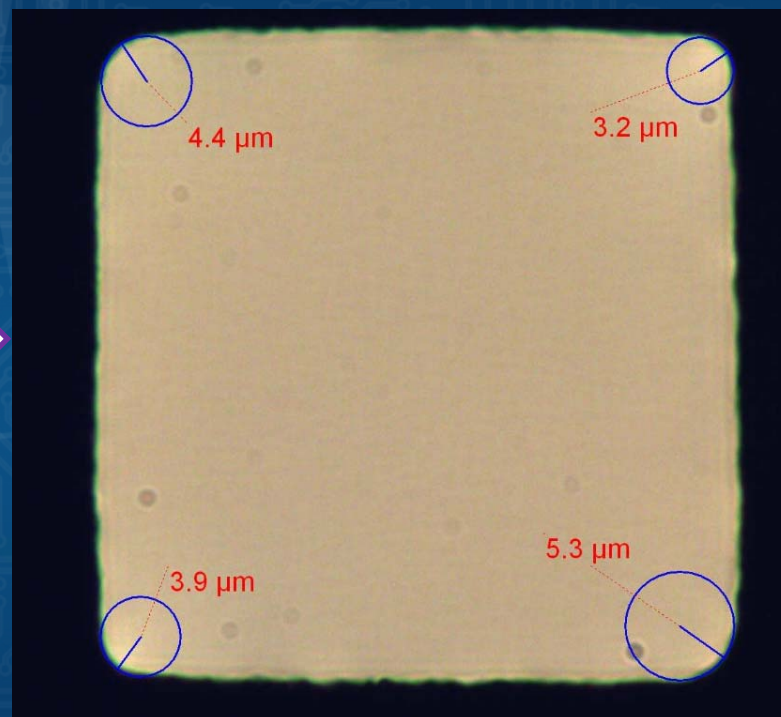
380um thick Silicon Nitride

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Preliminary Results



SMART



250 μm thick Silicon Nitride

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Preliminary Results

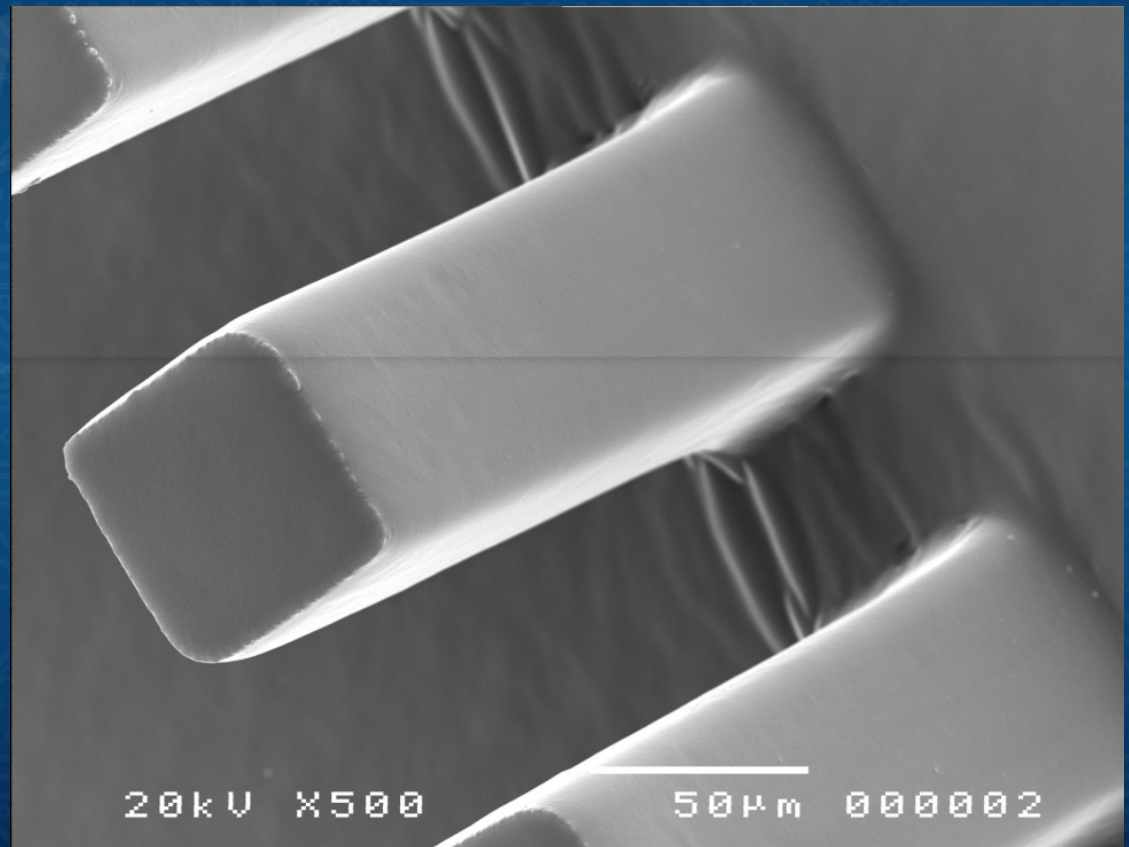
Material Thickness Si_3N_4	250μm	380μm
Old Method Range of Radii	6-8 μm	7-10 μm
New Method Range of Radii	4-5 μm	4.5-5.5

Preliminary Results

Cast of Square Hole

Smooth Hole Profile

Low Hole Taper



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What's Next

Next Production Steps :

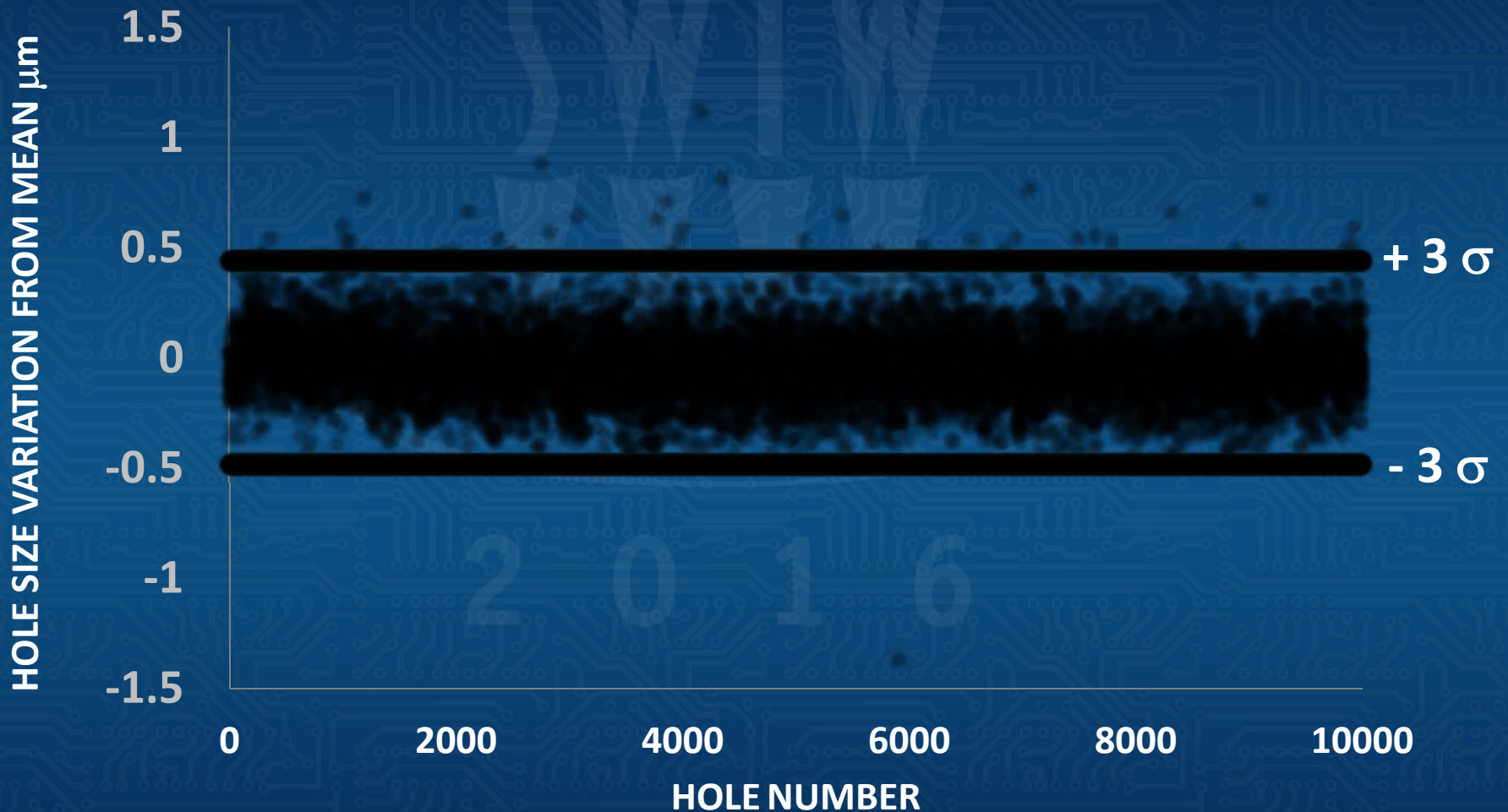
A.) Vigorously test and productionise Corner Radius Method

Next R&D Smart Steps :

A.) Reduce Hole Size Variation

B.) Reduce Hole Taper

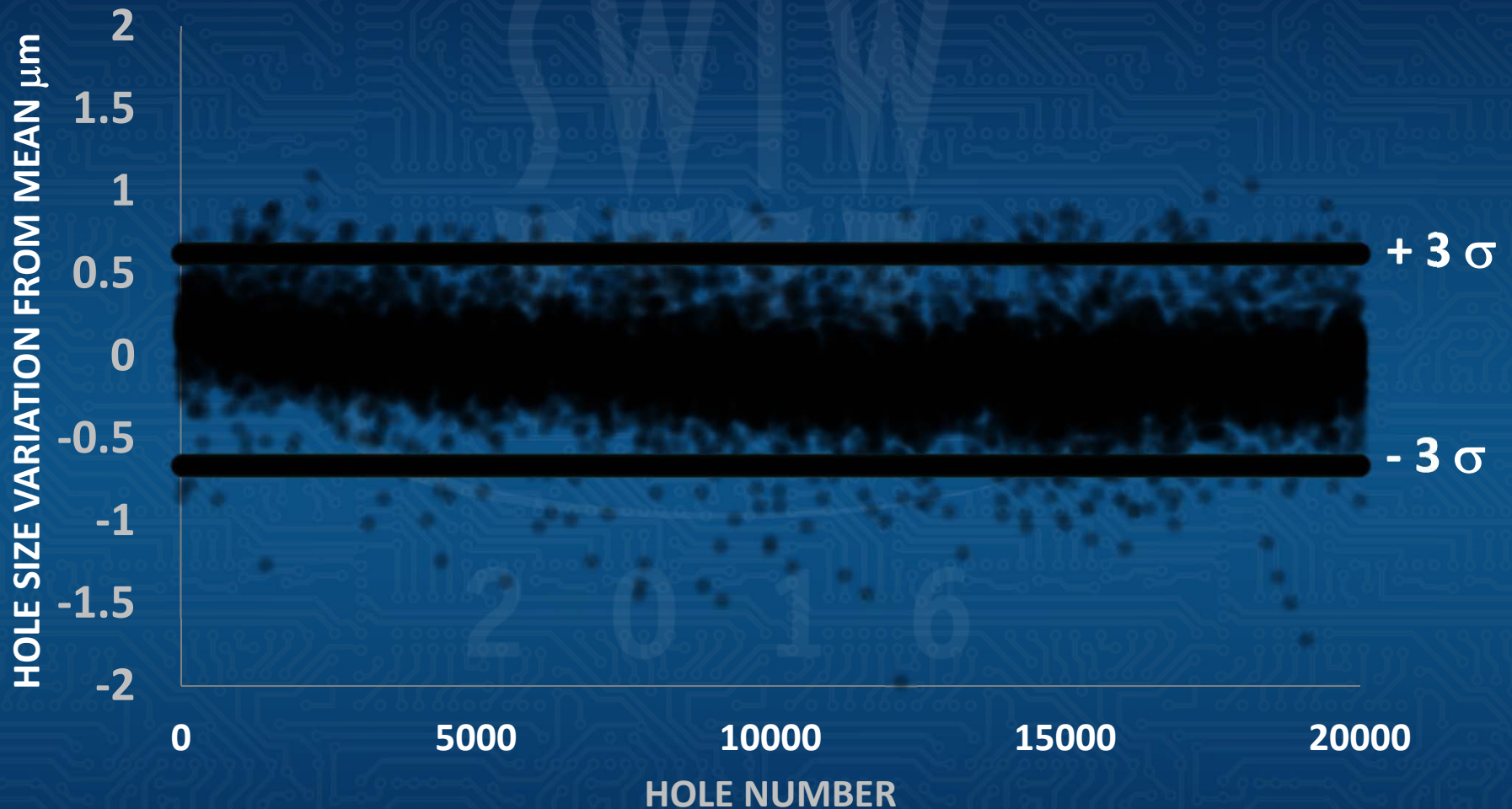
Hole Size Variation for 10,000 Holes



60 um by 60 um. 100-200um thick Silicon Nitride

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Hole Size Variation For 20,000 Holes

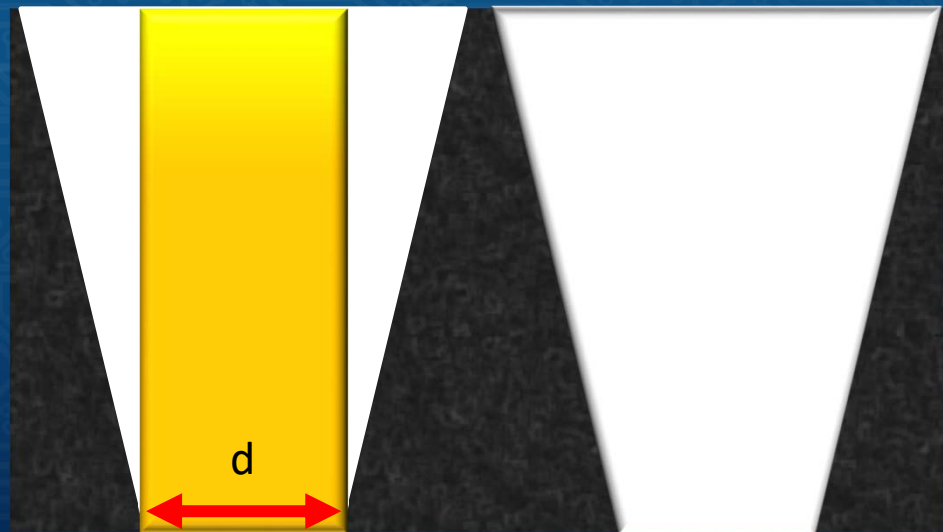
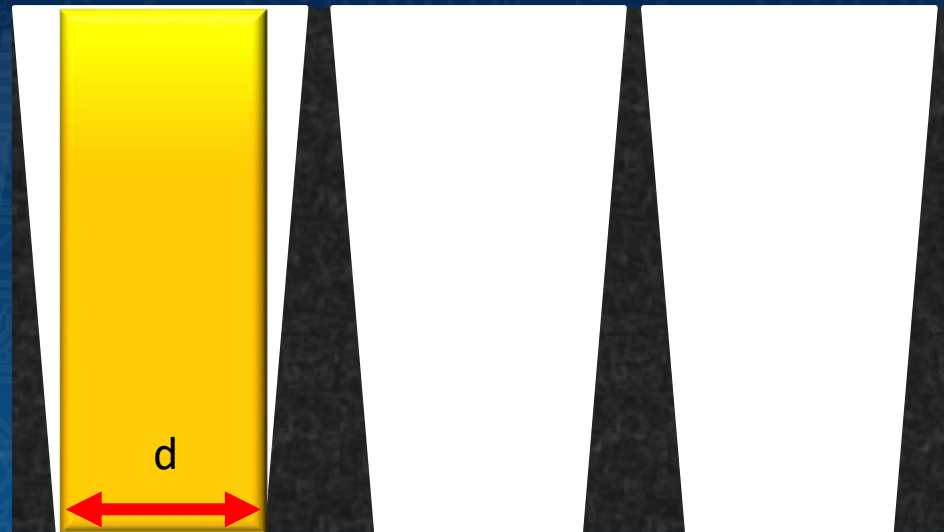


60 um by 60 um. 200-300 um thick Silicon Nitride

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Importance of Hole Taper

While the pin dimension “d” is the same, if we **reduce** the entrance diameter, then this **reduces the minimum pitch** of the holes



Summary

- **Smart Progress**
- **Tighter Corner Radius possible**
- **Research and Development is never complete there are always further improvements to be made**